MA2J1120G

Silicon epitaxial planar type

For switching circuits

■ Features

- Allowing high-density mounting
- Ensuring the forward current (Average) capacity $I_{F(AV)}$ = 200 mA

■ Package

- Code
  SMini2-F3
- Pin Name
  1: Anode
  2: Cathode

■ Marking Symbol: 1C

■ Absolute Maximum Ratings T_a = 25°C

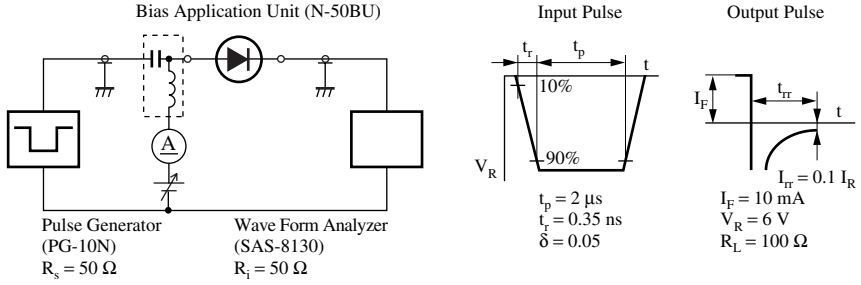
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	40	V
Maximum peak reverse voltage	V_{RM}	40	V
Forward current (Average) *1	$I_{F(AV)}$	200	mA
Peak forward current	I_{FM}	600	mA
Non-repetitive peak forward surge current *2	I_{FSM}	1	A
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

Note) ∗1: With a printed-circuit board
∗2: t = 1 s

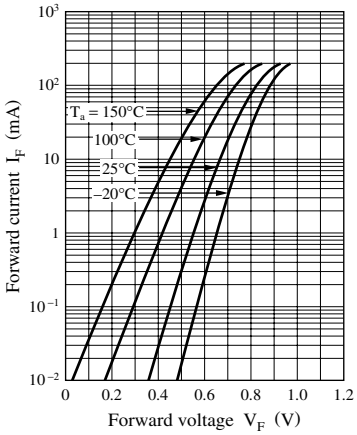
■ Electrical Characteristics T_a = 25°C ± 3°C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 200 mA			1.1	V
Reverse current	I_{R1}	V_R = 15 V			50	nA
	I_{R2}	V_R = 35 V			500	
	I_{R3}	V_R = 35 V, T_a = 100°C			100	µA
Terminal capacitance	C_t	V_R = 0 V, f = 1 MHz			4	pF
Reverse recovery time *	t_{rr}	I_F = 10 mA, V_R = 6 V I_{rr} = 0.1 I_R, R_L = 100 Ω			10	ns

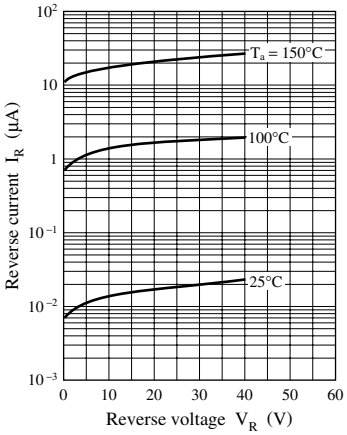
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 100 MHz.
3. ∗: t_{rr} measurement circuit



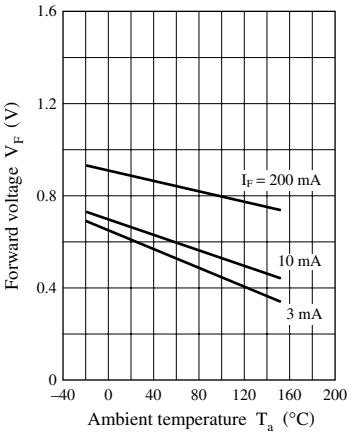
I_F — V_F



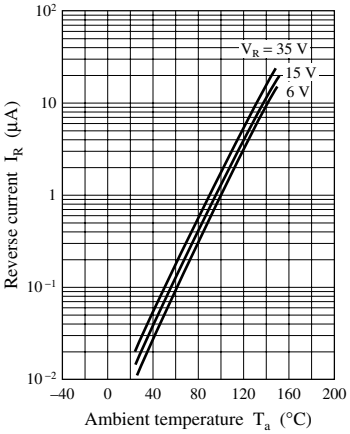
I_R — V_R



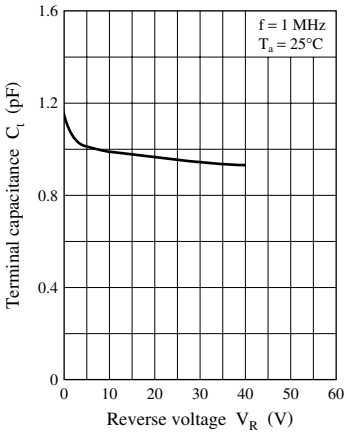
V_F — T_a



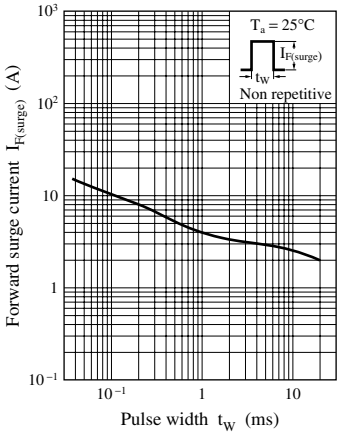
I_R — T_a



C_t — V_R

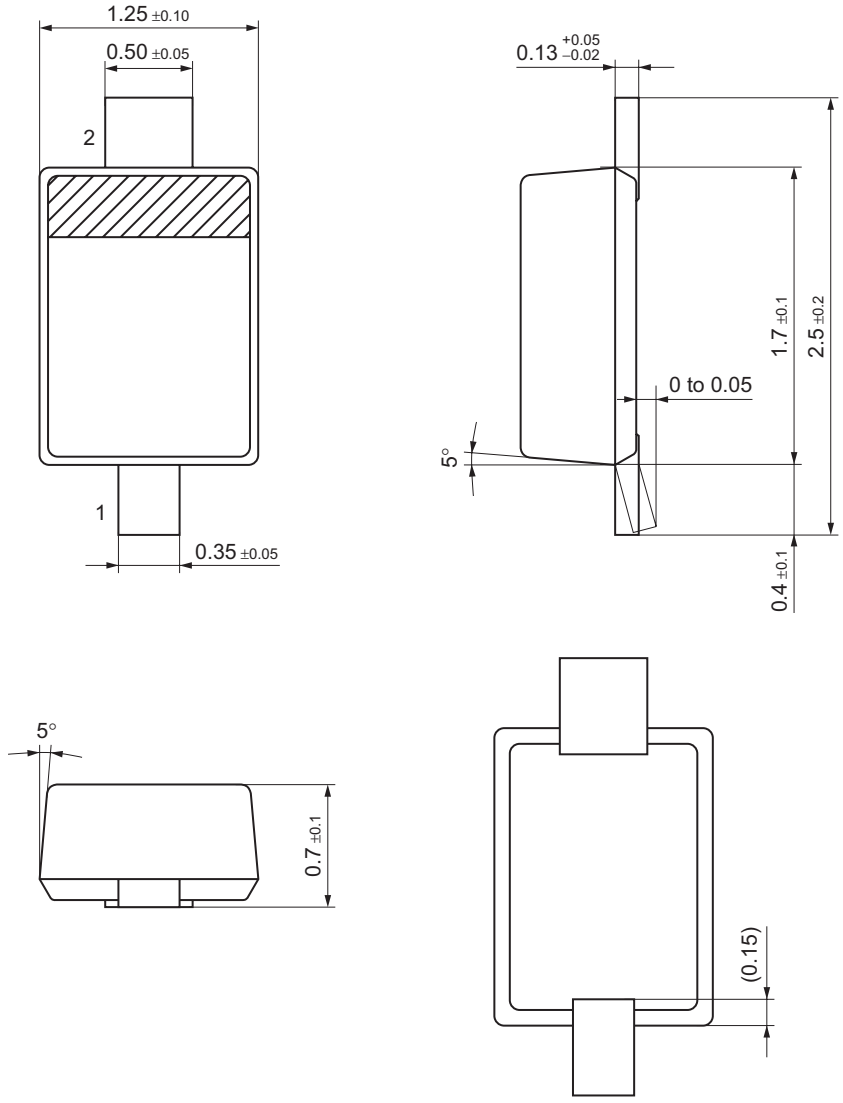


$I_{F(surge)}$ — t_W



SMini2-F3

Unit: mm



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